

## ABSTRACT OF THE DISCLOSURE

## COATING METHOD, COMPUTER STORAGE MEDIUM AND COATING APPARATUS

There is provided a coating method which can apply a coating solution uniformly onto a substrate surface while  
5 reducing the amount of the coating solution supplied. The coating method for applying a coating solution onto a wafer includes the steps of: supplying a solvent for the coating solution onto the wafer to form an annular liquid film of the solvent in a peripheral area of the wafer; supplying the  
10 coating solution to the center of the wafer while rotating the wafer at a first rotational speed (time  $t_1$ - $t_2$ ); and allowing the coating solution to spread on the wafer by rotating the wafer at a second rotational speed which is higher than the first rotational speed (time  $t_4$ - $t_5$ ). The  
15 supply of the solvent is continued until just before the coating solution comes into contact with the liquid film of the solvent (time  $t_0$ - $t_3$ ).

FIG. 8